

IN THE SPECIFICATION:

On page 1, line 1, please insert the following:

This is a divisional application of United States Patent Application Serial No. 09/741,239, filed on December 19, 2000, which is herein incorporated by reference for all purposes.

Please amend the paragraph starting on page 5, line 27 as follows:

Referring to Fig. 9, a semi-product before being subject to a plastic molding is formed by interconnecting the electronic device 3 and the frame leads 1 through a plurality of metal wires. It is clearly shown that the plurality of frame leads connected to the electronic device 3 of the semi-product are insulated with each other; therefore, the electronic characteristics of the semi-product can be measured before being subject to a plastic molding. Hence, the defective semi-products caused by welding are readily inspected. A defective component of the semi-product inspected before being subject to a plastic molding can be replaced by reworking of the semi-product. After conducting a plastic molding process, the semi-product is formed as shown in Fig. 10.